

SMD Power Inductor TVMP120611LNV-Series(N)-D

1. Features

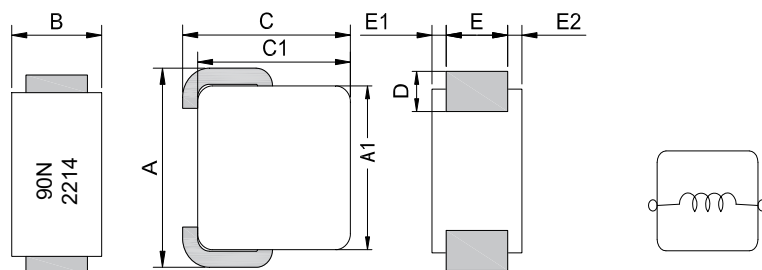
1. Low loss realized with low DCR.
2. High performance realized by metal dust core.
3. Ultra low buzz noise, due to composite construction.
4. 100% Lead(Pb)-Free and RoHS compliant.
5. High reliability -Reliability test complied to AEC-Q200.
6. Operating temperature:-55~+155°C (Including self - temperature rise)



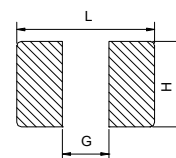
2. Applications

Automotive applications.

3. Dimensions



Recommend PC Board Pattern



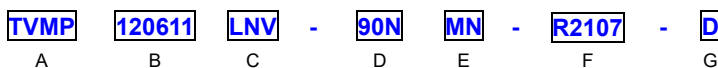
L(mm)	G(mm)	H(mm)
13.5	5.0	4.8

Note: 1.PCB layout is referred to standard IPC-7351B
 2. The above PCB layout reference only.
 3. Recommend solder paste thickness at 0.15mm and above.

Series	A	A1	B	C	C1	D	E	E1-E2
TVMP120611	12.7±0.4	10.3±0.2	5.8±0.2	11.2±0.3	10.4±0.2	3.3±0.3	4.2±0.2	≤0.5

Unit:mm

4. Part Numbering



- A: Series
 - B: Dimension
 - C: Type
 - D: Inductance
 - E: Inductance Tolerance
 - F: DCR
 - G: Code
- BxC.
Standard.
90N=0.09uH
M=±20%
- Marking: Black.90N and 2214 (22 YY, 14 WW, follow production date).

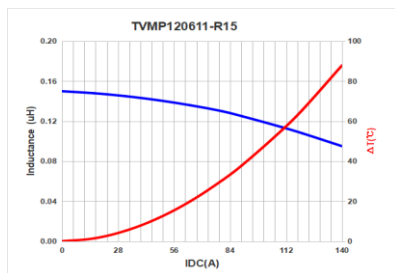
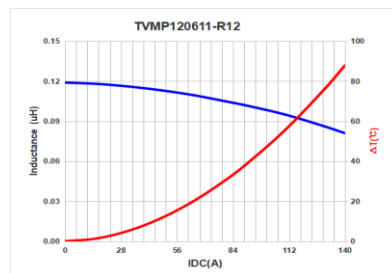
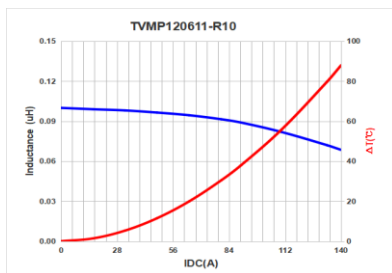
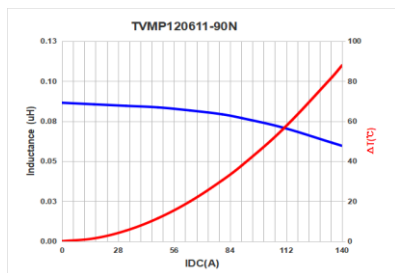
5. Specification

Part Number	Inductance L0 A(μH) ±20%	Heat Rating Current DC Irms (A)		Saturation Current DC(A)		DCR (mΩ)±7%	Marking
		Typ	Max	I sat 1 Typ	I sat 2 Typ		
TVMP120611LNV-90NMN-R2107-D	0.09	90.0	70.0	95.0	135.0	0.21	90N
TVMP120611LNV-R10MN-R2107-D	0.10	90.0	70.0	93.0	133.0	0.21	R10
TVMP120611LNV-R12MN-R2107-D	0.12	90.0	70.0	91.0	130.0	0.21	R12
TVMP120611LNV-R15MN-R2107-D	0.15	90.0	70.0	87.0	120.0	0.21	R15

Note:

1. Test frequency : L_s : 100KHz /1.0V.
2. All test data referenced to 25°C ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C
5. Saturation Current (Isat1) will cause L0 to drop approximately 20%.
Saturation Current (Isat2) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 155°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Irms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components.
Therefore temperature rise should be verified in application conditions.
8. Rated DC current: The lower value of Irms and Isat

6. Typical Performance Curves



单击下面可查看定价，库存，交付和生命周期等信息

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